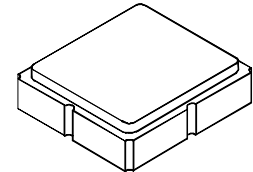


SF2485E

868 MHz
SAW Filter



SM3030-8

- **Low-loss UHF SAW Filter**
- **3.0 x 3.0 mm Surface-mount Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

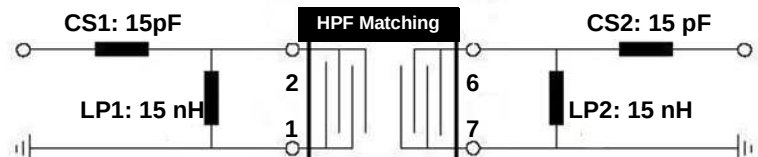
Maximum Rating

Rating	Value	Units
DC Voltage on any Non-ground Terminal	3	V
Input Power Level: Pass Band	33	dBm
Stop Band	15	dBm
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-10 to +60	°C
Storage Temperature Range	-40 to +85	°C
Moisture Sensitivity Level	1	MSL
Solder Reflow Temperature, 5 Cycle Maximum	260°C for 10 seconds	

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			868		MHz
Maximum Insertion Loss, 698 to 758 MHz	IL_{MAX}			1.0	3.5	dB
758 to 803 MHz				1.9	3.5	
803 to 821 MHz				1.9	3.5	
821 to 862 MHz				4.0	6.0	
880 to 925 MHz				1.1	3.5	
925 to 960 MHz				1.0	3.5	
1710 to 1805 MHz				1.7	3.5	
1805 to 1880 MHz				1.8	3.5	
2110 to 2170 MHz				2.1	3.5	
2620 to 2690 MHz				2.5	3.5	
Attenuation, 0 dB Reference: 867 to 869 MHz			20	24		dB
Temperature Coefficient of frequency				-36		ppm/k
Source Impedance Z_S				50		ohm
Load Impedance Z_L				50		

Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint		
Lid Symbolization, Y=year, WW=week, S=shift, dot=pin 1 indicator	D6_YWWS		
Standard Reel Quantity	Reel Size 7 inch	500 Pieces/Reel	
	Reel Size 13 inch	3000 Pieces/Reel	

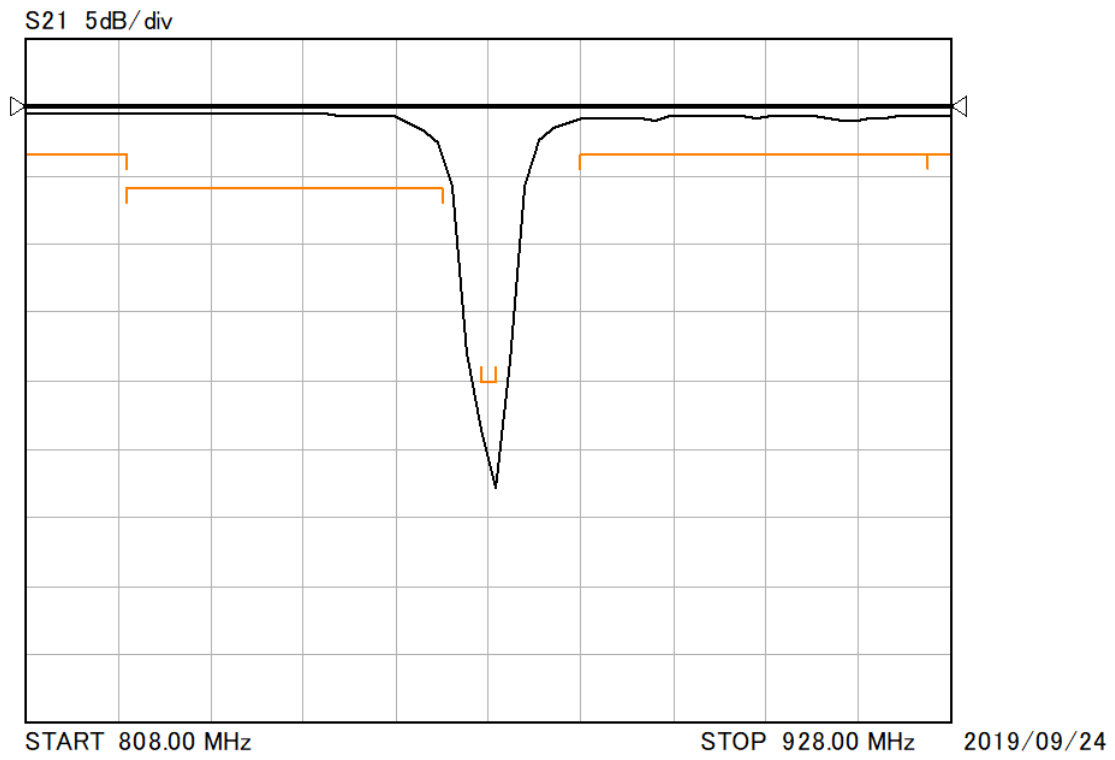
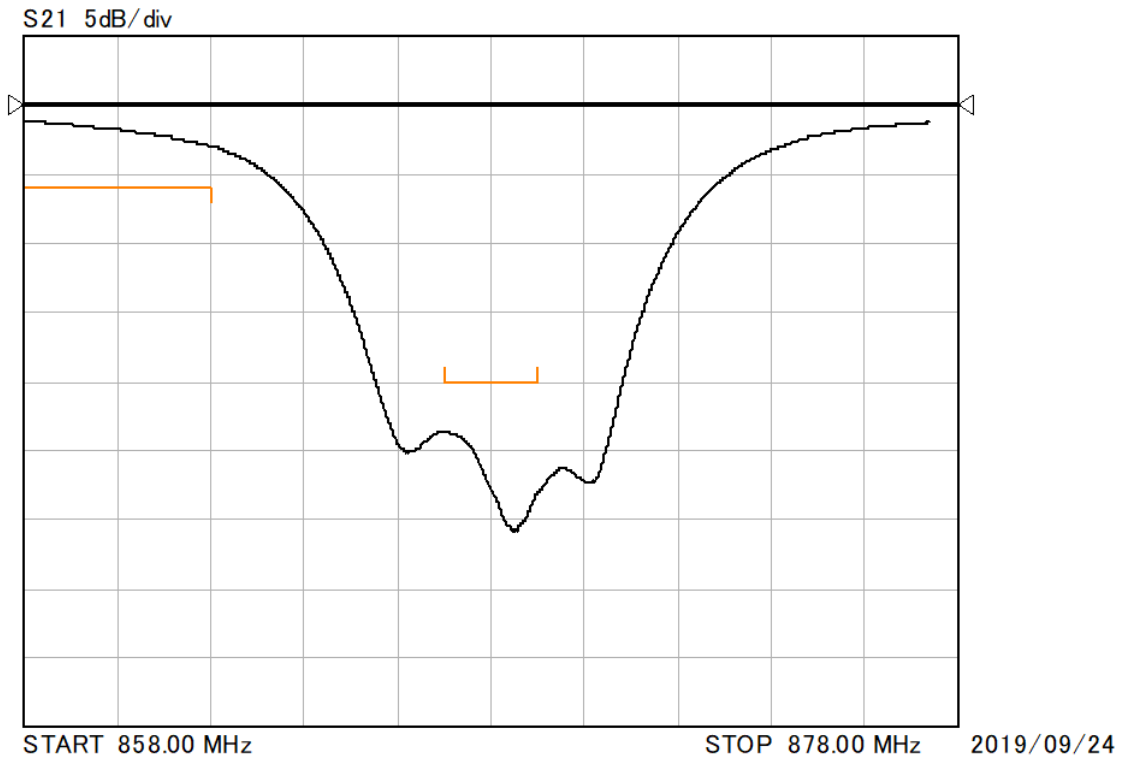
Electrical Connections	
Input	2
Output	6
All Others	1, 3, 4, 5, 7, 8



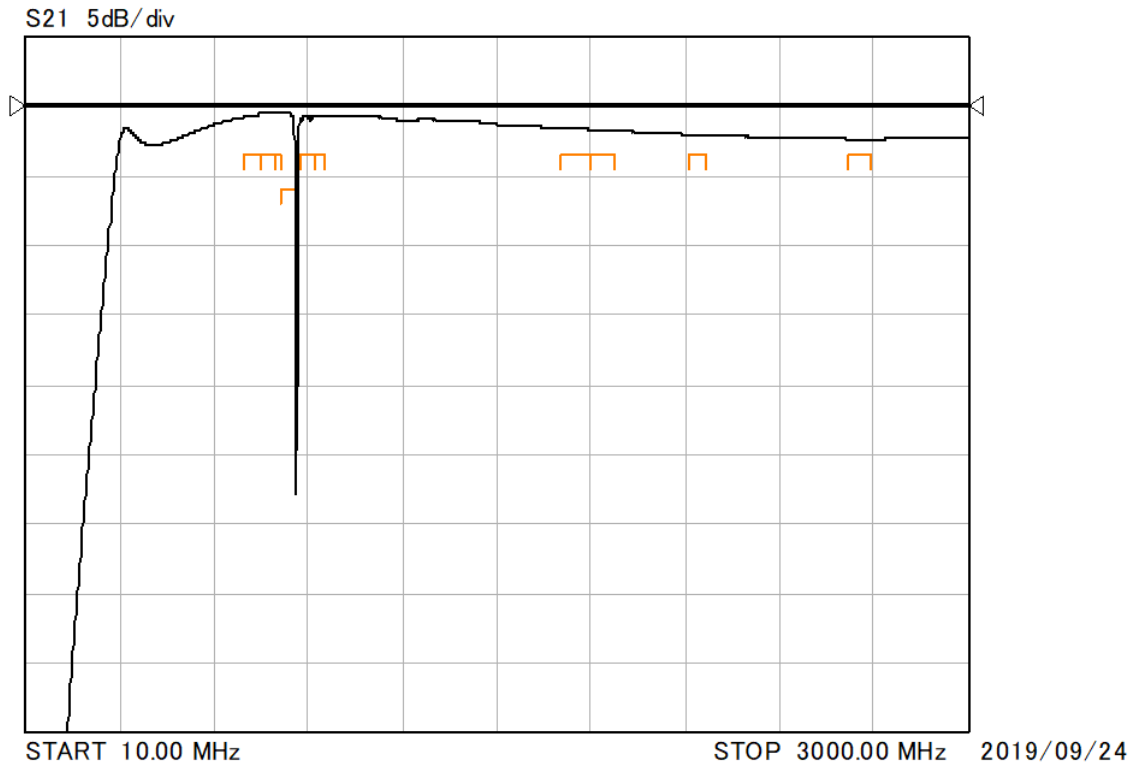
 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

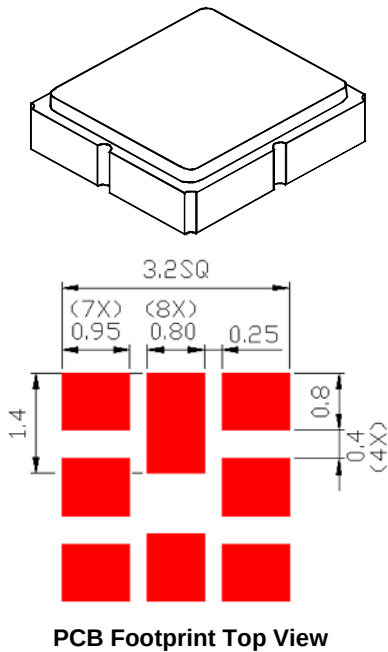
Frequency Characteristics



Frequency Characteristics (cont.)



8-Terminal Ceramic Surface-Mount Case 3.0 x 3.0 mm Nominal Footprint



Case and PCB Footprint Dimensions

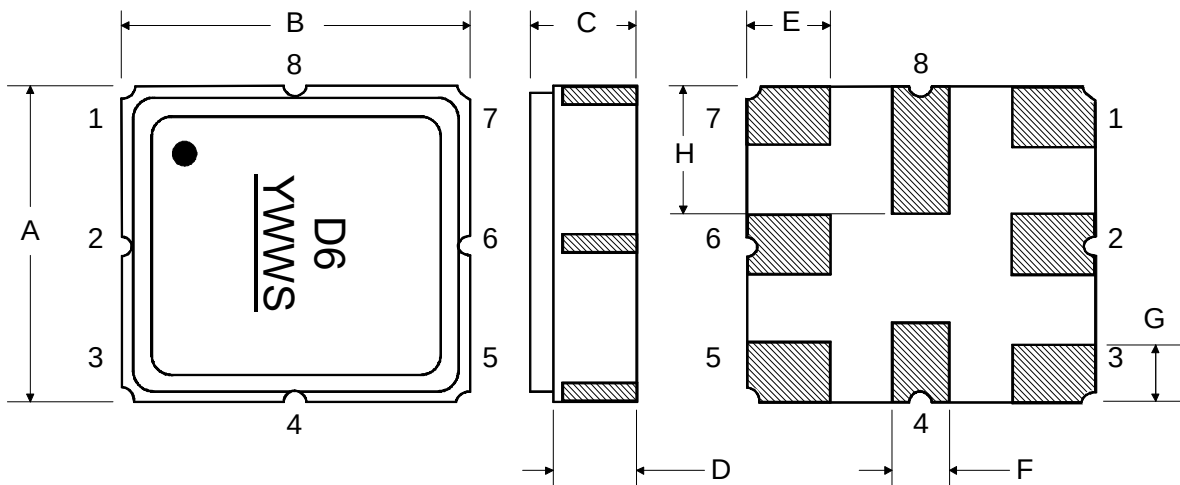
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.90	3.00	3.10	0.114	0.118	0.122
B	2.90	3.00	3.10	0.114	0.118	0.122
C	0.90	1.00	1.10	0.035	0.039	0.043
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.023	0.028
G	0.50	0.60	0.70	0.019	0.023	0.027
H	1.10	1.20	1.30	0.043	0.047	0.051

Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW

BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

